

3 a ball grid array electronic package including a plurality of contacts thereon;

4 a plurality of round solder balls, each of said round solder balls electrically coupling one  
5 of said plurality of contacts on said substrate to a respective one of said plurality of  
6 contacts of said ball grid array electronic package;

7 a first joining medium adapted for electrically connecting each of said round solder balls  
8 to respective ones of said plurality of contacts of said ball grid array electronic package;  
9 and

10 ( a second joining medium adapted for electrically connecting each of said round solder  
11 balls to respective ones of said plurality of contacts of said substrate, said contacts of said  
12 substrate each being of a substantially quadrilateral shape having a diameter slightly  
13 larger than the diameter of the corresponding round shape of said solder balls so as to  
14 project externally from said round shape and present said substantially quadrilateral shape  
15 when viewed by X-Ray from above said ball grid array electronic package and thereby  
16 indicate that said second joining medium electrically connects said solder balls to  
17 respective ones of said contacts on said substrate.

18 10. The electronic assembly of claim 9 wherein said plurality of contacts on said substrate are  
19 substantially square in shape.

20 11. The electronic assembly of claim 9 wherein said substrate is a printed circuit board.

21 12. The electronic assembly of claim 9 wherein said first and second joining mediums are  
22 each comprised of solder paste.--